



Material Content Data Sheet



Sales Product Name		ITS42008-SB-D		Issued		29. August 2013		
MA#		MA001122786						
Package		PG-DSO-36-26		Weight*		2046.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	16.733	0.82	0.82	8177	8177
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		187	
	non noble metal	zinc	7440-66-6	1.533	0.07		749	
	non noble metal	iron	7439-89-6	30.652	1.50		14979	
	non noble metal	copper	7440-50-8	1244.598	60.82	62.41	608201	624116
wire	noble metal	gold	7440-57-5	4.281	0.21	0.21	2092	2092
encapsulation	organic material	carbon black	1333-86-4	1.443	0.07		705	
	plastics	epoxy resin	-	66.356	3.24		32426	
	inorganic material	silicondioxide	60676-86-0	653.457	31.93	35.24	319326	352457
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7892	7892
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	362	362
solder	noble metal	silver	7440-22-4	0.151	0.01		74	
	non noble metal	tin	7440-31-5	0.100	0.00		49	
	non noble metal	lead	7439-92-1	9.784	0.48	0.49	4781	4904
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com